	Material Compo © Copyright 2005. If international and Pan	Osition Dec PC, Bannockb -American co	c laration ourn, Illinois. A opyright conve	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	ion of th encompa	e substance asses all low	s within the er level mat	manufactur erials for wl	er listed it hich the m	em. Note: anufacture	if the item is an as er has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-04-24			
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item 2SC6097						Effective Date	Date Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type	
							2024-04-24 CNG			3	29.0	mg	Each		
/Ianufa	cturing Proccess Informat	tion		·				•							
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020 N		-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Ter		Temperat	ire Num	ber of Reflow Cyc	les	
contains Bi		CU Alloy	U Alloy NA			0 C		30		second	ls 3				
omments	3														
or more	information regarding material	composition	please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.44	mg	Supplier	Silicon (Si)	7440-21-3		0.44	mg
Die Attach Solder	0.22	mg	Supplier	Silver (Ag)	7440-22-4		0.0055	mg
			А	Lead (Pb)	7439-92-1	7a	0.2035	mg
			Supplier	Tin (Sn)	7440-31-5		0.011	mg
Lead Frame	191.35	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.6994	mg
Mold Compound-Black	130.26	mg		Brominated epoxy resin	proprietary data		1.8236	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8617	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1723	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.695	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		22.1442	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2605	mg
Plating	6.31	mg	В	Bismuth (Bi)	7440-69-9		0.0379	mg
			Supplier	Tin (Sn)	7440-31-5		6.2721	mg
Wire Bond - Au	0.42	mg	Supplier	Gold (Au)	7440-57-5		0.42	mg